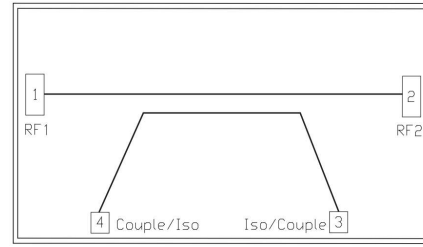


Performance

- Frequency: 1.2~1.4GHz
- Coupling: 25dB
- Directivity: ≥ 20 dB
- Chip size: 2.2*1.3*0.1mm

Function Diagram

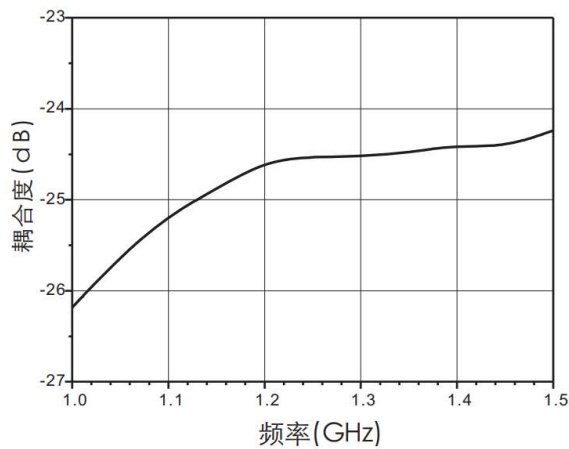


Electrical Specifications (Ta=+25°C, 50Ω system)

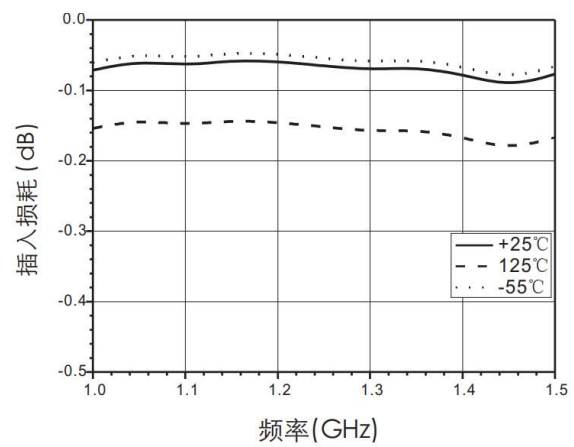
Parameter	Min	Typical	Max	Unit
Frequency Range	1.2~1.4			GHz
Coupling	24	25	26	
Insertion Loss	-	0.1	-	dB
Input Return loss	-	20	-	dB
Thru Output Return loss	-	20	-	dB
Coupling Output Return loss	-	20	-	dB

Test Curves (Die chip + Bonding line test)

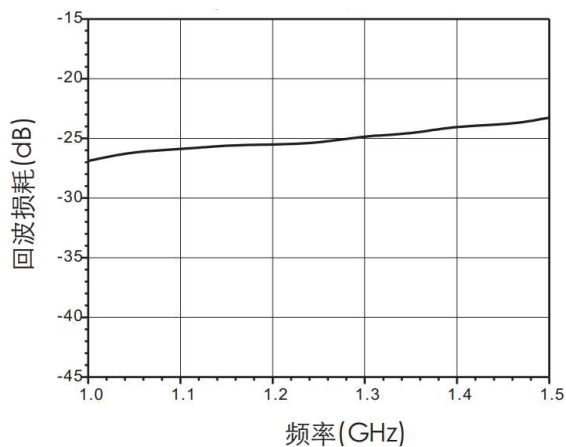
Coupling vs. Freq



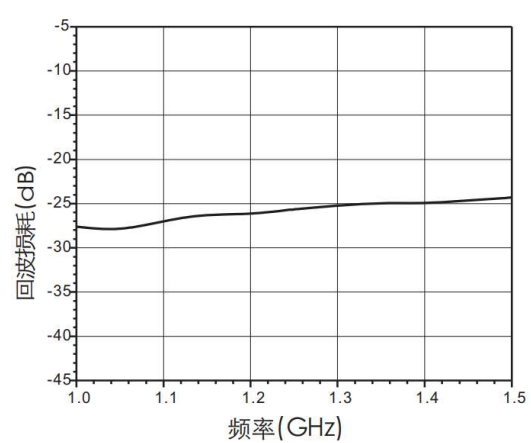
Insertion loss vs. Freq

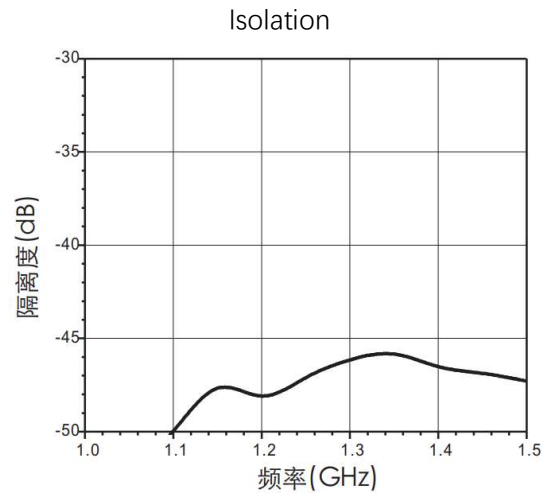
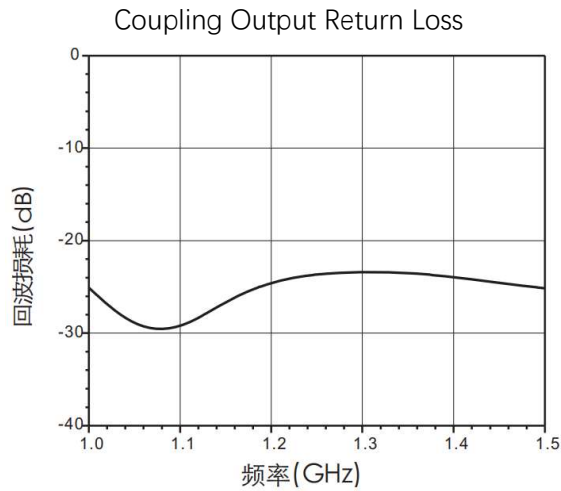


Input Return Loss vs. Freq

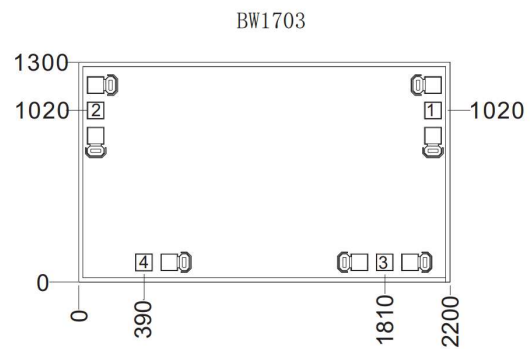
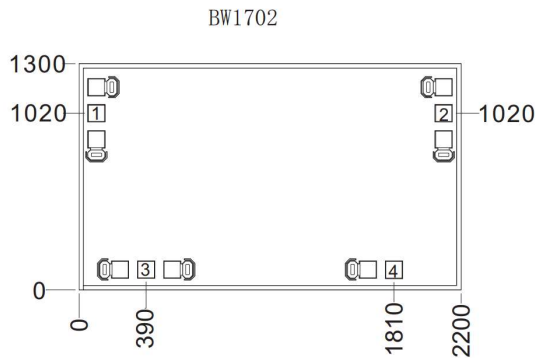


Thru output Return loss vs. Freq





Outline Size



1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated,
Pad size: $100 \times 100 (\mu\text{m})$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Absolute Rating

Storage Temperature	$-65 \sim +150^{\circ}\text{C}$
Operating Temperature	$-55 \sim +125^{\circ}\text{C}$
Max Input Power	50W
Static Protection (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3	Couple	Coupling ouput
4	ISO	Isolation

Application

